

2019 Spacecraft Thermal Control Workshop

High Performance Thermal Switch for Lunar Night Survival

D. Bugby

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Outline

- Introduction
- Background
- Concept
- Design
- Fabrication
- Testing
- Conclusion

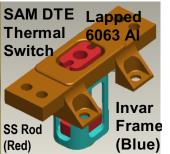
- ... objective, approach, results
- ... related device development history
- ... basis of operation for invention
- ... layout, materials, dimensions
- ... key build processes/techniques
- ... qualification test program to TRL6
- ... implications for flight implementation



Introduction

- **OBJECTIVE**: To enable future NASA/JPL solar/battery (non-radioisotope, night-survivable) lunar instruments, the development goal was a thermal switch that would outperform the **100:1** MER paraffin thermal switch by at least 10X
- APPROACH: Utilize differential thermal expansion (DTE) but reverse the operation of normal-operation DTE thermal switches (e.g., those for the Curiosity SAM instrument, cryocooler redundancy) that are OFF/warm, ON/cold ... lunar instrument need: ON/warm, OFF/cold
- **RESULTS:** Two reverse-operation DTE thermal switch prototypes were built as illustrated in graphic to the right; these units have a measured G_{ON} = 5 W/K, G_{OFF} = 0.002 W/K, G_{ON}/G_{OFF} ratio of **2500:1** ... **25X MER Thermal Switch!!** This briefing describes their development and qualification to TRL6





JPL Reverse-Operation DTE Thermal Switch Fully Autonomous Patent-Pending

DESIGN-1

DESIGN-2





Body: Aluminum **Rod:** Invar/Ultem 2300

Alum/Ultem 1000 Invar/Ultem 2300

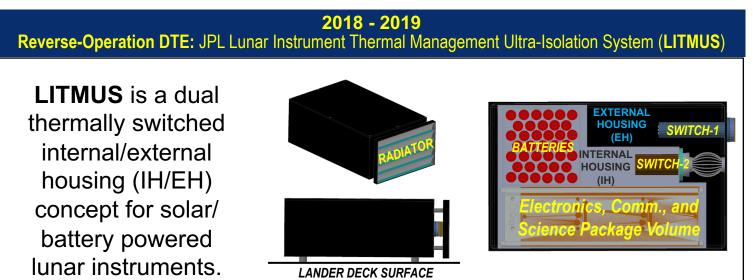


Background

Evolution/History: conical gas-gap → flat gas-gap → normal-operation DTE → reverse-operation DTE. As a result, JPL is developing the LITMUS dual thermally switched nested enclosure concept for lunar night survival.





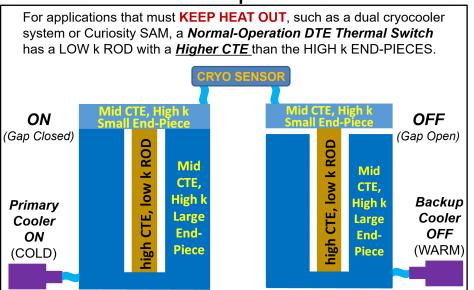




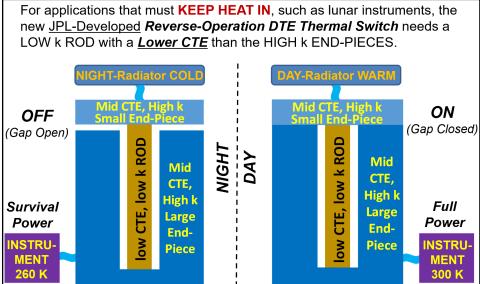
Concept

DTE thermal switch actuation due to the mating/de-mating of parallel, flat, near mirror finish metal surfaces. Motion caused by DTE of mid-CTE, high k metal end-pieces vs. high-CTE (normal) or low-CTE (reverse), low k rod.

Normal-Operation



Reverse-Operation

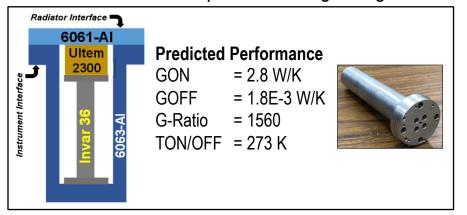




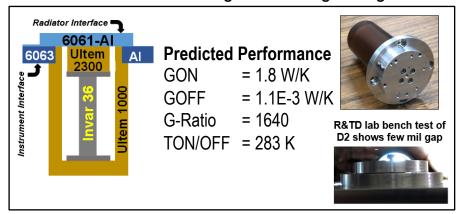
Design

Thermal switch prototypes designed for flanged attachment to instrument enclosures, requiring 25-35 mm diam. opening so most of 80-130 mm length is inside; two 35-55 mm diam., 6 mm thick discs externally visible.

DESIGN-1: Compact Mounting Flange



DESIGN-2: Heritage Mounting Flange

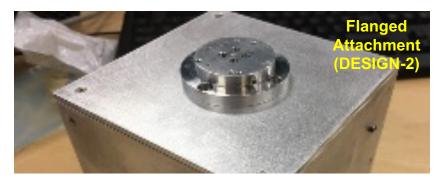


Envelope: Length = 126 mm, Max. Diameter = 35 mm

Mass: 137 grams

Envelope: Length = 86 mm, Max. Diameter = 55 mm

Mass: 142 grams





Fabrication

Conventional machining used except for mating surface preparation. For good ON performance, mating surfaces must be extremely smooth and highly parallel. A few key fabrication steps/features are indicated below.

Mating surfaces hand-lapped and polished to *near mirror finish*Bosses in Invar 36 and Illtem 2300







Bosses in Invar 36 and Ultem 2300 keep parts in stable position —

• Machine, profile scan of rod on endpiece for parallelism, offset (δ_1) ——•

Bellville washers (used on some previous DTE switches) *not used*



Parallel but out of plane (lower) by

Parallel to

<<< 1 mil



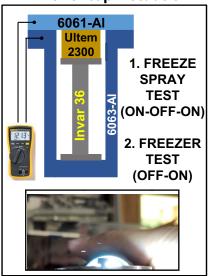
design offset (δ_1)



Testing: Overview

STEPS to TRL6: (1) Benchtop actuation test (elec.); (2) TVAC G_{ON}/G_{OFF} and cycling test; (3) Vibration test with TVAC pre/post-test thermal; and (4) TVAC in relevant environment (hi-fidelity, long duration, model verif.).

1. Benchtop Actuation

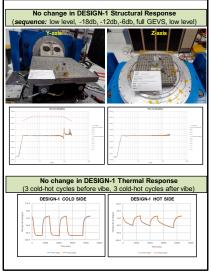


Mar 2018

Setup-2: OFF Testing Setup-3: Cycling Setup-3: Cycling Setup-3: Cycling HTR Setup-3: Cycling HTR Setup-4: QM Cal w/ Heater Setup-5: QM Cal Adj.

Apr 2018 - July 2018

3. Vibe + TVAC Thermal



Sep 2018 - Oct 2018

4. TVAC Rel. Environment

Thermal
Switches
Mounted to
Instrument
Cubes (IC)



ICs MLI Blanketed, Radiator Attached, Suspended by Kevlar Cables to Alum. Shroud, Shroud Mounted to LN₂ Plate



36-Day Simulation: Six 6-Day Cycles 3 Days HOT → 288 K Al Shroud Bottom 3 Days COLD → 88 K Al Shroud Bottom

Dec 2018 – Jan 2019

TRL3

TRL3-4

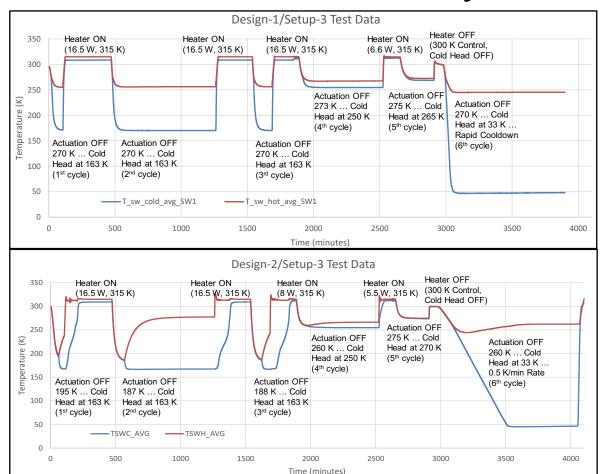
TRL4-5

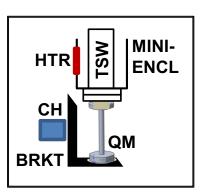
TRL6



Testing: Step 2 Cycling

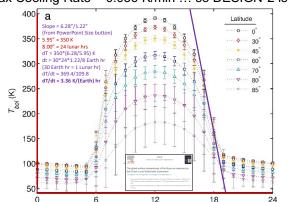
Cycling revealed that ON-to-OFF and OFF-to-ON actuation temps of Design-2 are sensitive to cooling/heating rate but those of Design-1 are not. On lunar surface, **rates are very low** so both prototypes are viable.







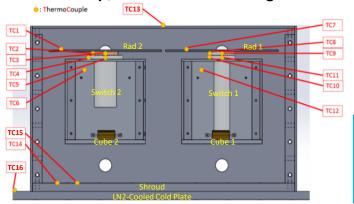
Lunar Surface Temperature Diviner Data Max Cooling Rate = 0.056 K/min ... so DESIGN-2 is Viable



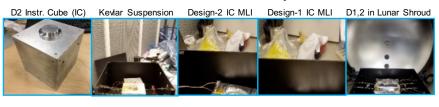
Testing: Step 4 Summary

The Step 4 TVAC test showed that both thermal switches have highly repeatable, nearly identical ON/OFF performance. An exception to this is a 15 K Δ T evident on 4th cold cycle that was not there on 6th cold cycle.

Test Setup, Instrumentation Diagram



Photos of Test Setup





Lunar Simulation Test Plan/Status

• Six 3-day Cold Half-Cycles: TLN2 plate = 88 K, IC Q = 0-1.5 W • Six 3-day Hot Half-Cycles: TLN2 plate = 280 K, IC Q = 8 W

• Total Test Duration: 36 days (6 Six-Day Cold-Hot Full Cycles)

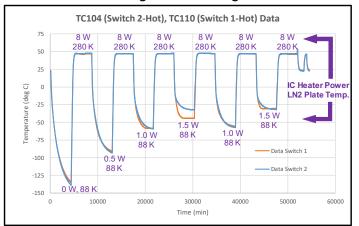
• Lunar 30-Day Cycle: Accelerated by 5X

Test Start Date/Time:
 Test End Date/Time:
 Test Status:
 11/30 at 11:40am (1st Cold Half Cycle)
 1/5 at 11:40am (end of 6th Hot Half Cycle)
 completed (short 7th Hot Mini-Cycle added)

Top-Level Summary/Assessment of Results

Highly repeatable, predictable ON/OFF performance; few noted exceptions ... During 4th cold cycle (1.5 W), Switch 1-Hot got about 15 K cooler vs. Switch 2-Hot. During 6th cold cycle (1.5 W), this effect was not observed in the data. Upon removal of setup, *one Switch 2, two Switch 1 Kevlar cables had broken.* Impact likely minimal (see photos later) but may explain 4th cold cycle anomaly if: Switch 1 cables broke separately: 1st caused side loads, 2nd eliminated them. Switch 2 more resistant to side loads, so single break was not a problem.

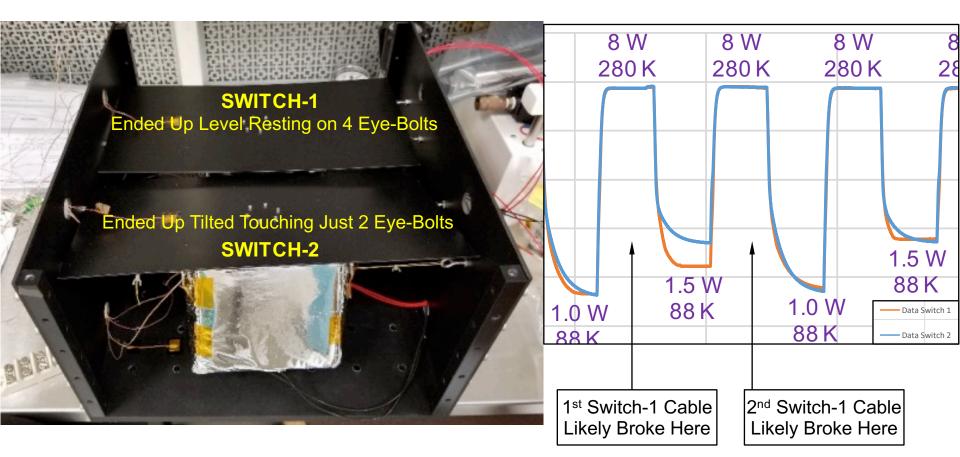
Test Data: Design-1 vs. Design-2 Hot Side





Testing: Step 4 Issue

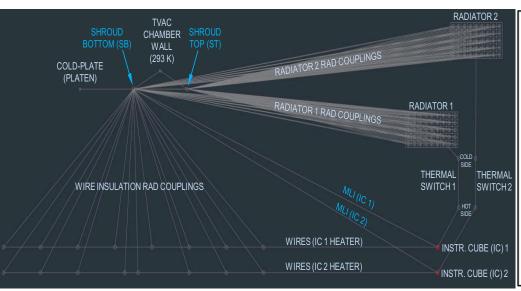
Upon removal from TVAC, one Switch-2, two Switch-1 Kevlar cables had broken. Impact was minimal (see photo). It is theorized that the Switch-1 cables broke separately: 1st caused side loads, 2nd eliminated them. Switch-2 more resistant to side loads so single break was not problem.

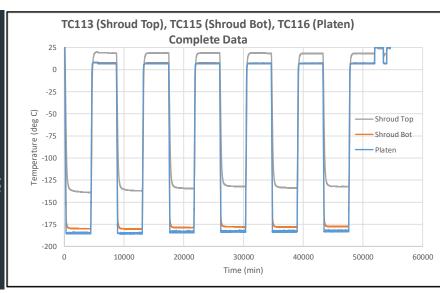




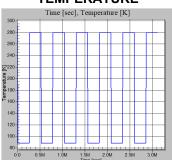
Testing: Step 4 Model

Test thermal model developed with just 3 correlating inputs (G_C , G_R , ϵ^*), where G_C = conductance from shroud top to bottom, G_R = radiative coupling from shroud top to bottom, and ϵ^* = MLI effective emittance.

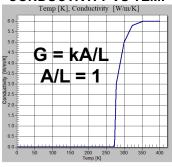




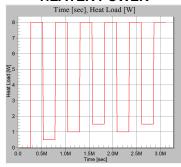
COLD-PLATE (PLATEN) TEMPERATURE



THERMAL SWITCH
CONDUCTIVITY VS TEMP



INSTRUMENT CUBE HEATER POWER



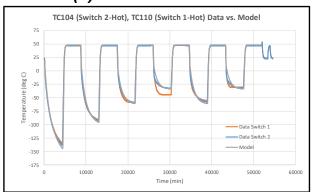
Correlated Model Inputs

 $G_C = 0.15 \text{ W/K}$ $G_R = 0.13 \text{ m}^2$ $\epsilon^* = 0.04$

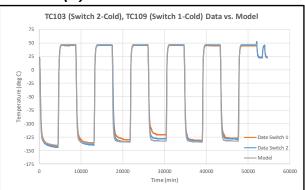
Testing: Step 4 Data vs Model

Test thermal model results agree with measured data (except for cycle 4 issue) to within about 5 K over the entire system including: (a) switch hot side; (b) switch cold side; (c) radiator; (d) shroud top; (e) shroud bottom.

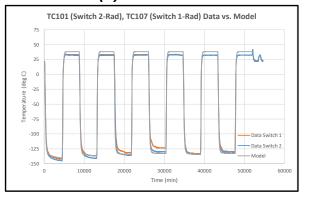
(a) Switch Hot Side



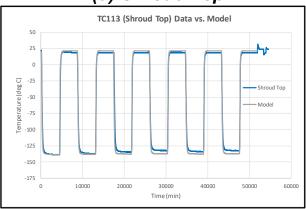
(b) Switch Cold Side



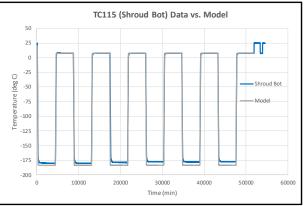
(c) Radiator



(d) Shroud Top

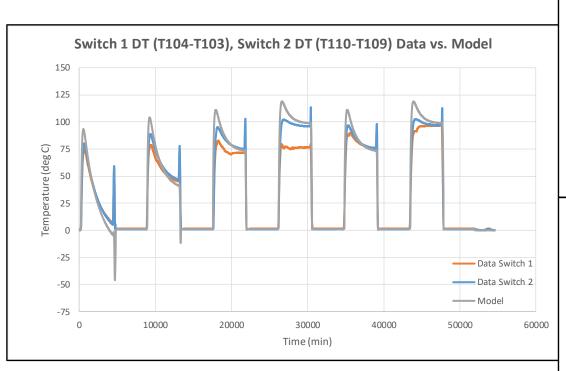


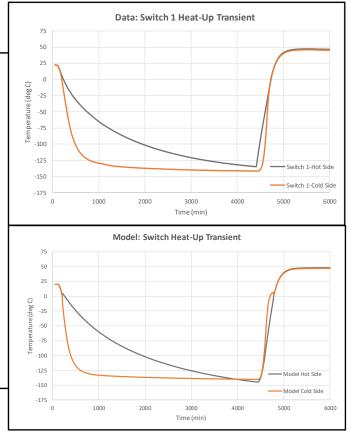
(d) Shroud Bottom



Testing: Step 4 Data vs Model (cont'd)

The model predicts higher DT early in cold cycles but difference shrinks in time. By cold cycle end, model and data very close (except cycle 4). Large short-lived deviation occurs at start of each hot cycle as model cold side heats up faster than data (so data DT > 0, model DT < 0).

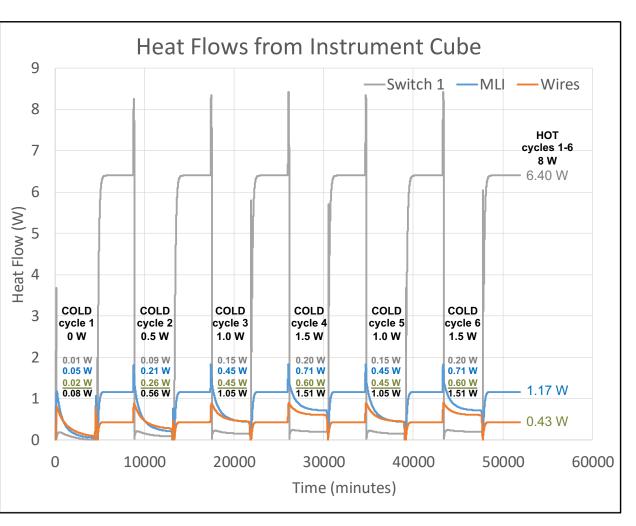






Testing: Step 4 Model Heat Flows

Model used to predict heat flows via **switch vs MLI vs wires**. Results indicate where to focus effort in future lunar instrument thermal packages.



Assuming the thermal model is reasonably close to reality, about 85% of the cold case heat loss in this test configuration was due to wires and MLL.

These predictions underscore why future lunar instruments need the following (in addition to superior thermal switches):

- (1) High performance MLI
- (2) Isolative structural mounts
- (3) Low heat loss feed-throughs

NOTE: Differences between applied power and heat flow totals due to IC not reaching complete steady-state (even after 3 days of cooling)



Conclusion

 JPL reverse-operation DTE thermal switch development and qualification test program has been successfully completed

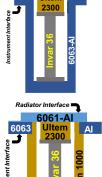
STEP 1 - Design/build/bench test (11/17 - 4/18)
 STEP 2 - TVAC performance test (4/18 - 7/18)
 STEP 3 - Vibration test (9/18 - 10/18)
 STEP 4 - High fidelity (lunar sim) test (12/18 - 1/5)

 Both JPL reverse-operation DTE thermal switch prototypes are at TRL6 based on completing all requirements in the table below

From NPR 7123.1e Criteria from NPR 7123.1e n Req. e/ Function	Ta	able 3.1.3-1: TRL Definition and Decomposition by Factor							
subsystem model or demonstrating agreement with demonstrate d in a relevant environment en	R	from NPR	Criteria from			Fidelity of Analysis			Environment Verification
mechanis	6	subsystem model or prototype demonstrate d in a relevant	performance demonstrating agreement with analytical	•	functionality/ performance demonstrate	predict key performance parameters and life limiting factors as a function of operational	prototype that addresses all critical scaling	,	Tested in relevant environment s. Verify by test that the technology is resilient to the effects of life-limiting mechanisms







Both JPL reverse-operation DTE thermal switch prototypes are ready for LITMUS or another comparable lunar flight experiment



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